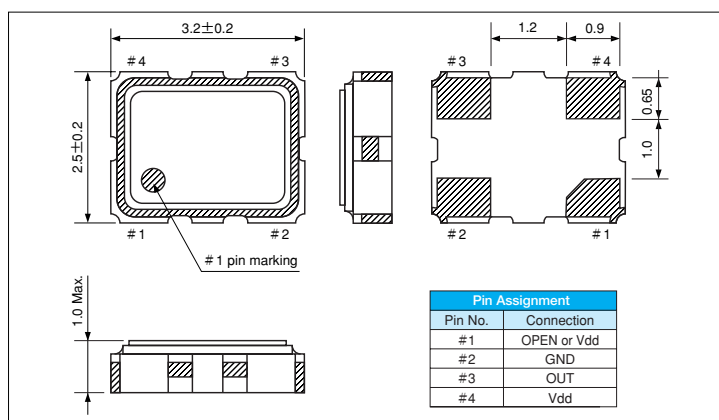




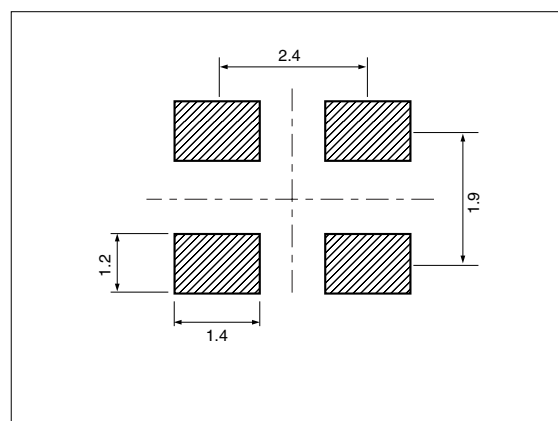
FEATURES

- High-density SMD type.
- Ultra-light weight and ultraminiature size.
- Low current consumption.
- Suitable for various applications such as communication devices, AV devices, automotive devices and measuring instruments.
- Automatic mounting and reflowable Type.

DIMENSION [mm]



SOLDER PAD LAYOUT [mm]



STANDARD SPECIFICATIONS

* Model is determined by the selection for the output enable or stand-by function, the frequency stability and the supply voltage.

Item	Model	CSX-325F (@) (*)	
Frequency Range		12.500MHz~54.000MHz	
Supply Voltage	(*)	H : Vdd=2.5V±0.1V	J : Vdd=3.3V±0.1V
Frequency Stability	(@)	B : ±50ppm, C : ±100ppm, E : ±50ppm(−40℃~+85℃), F : ±100ppm(−40℃~+85℃)	
Operating Temperature Range		−20℃~+70℃ (−40℃~+85℃)	
Storage Temperature Range		−55℃~+125℃	
Current consumption	(No load)	5mA Max. (<30.0MHz) / 7mA Max. (<54.0MHz)	
Duty	CMOS level (1/2 Vdd)	40~60%	
Output Voltage	V _{OH}	0.8Vdd Min.	
	V _{OL}	0.2Vdd Max.	
Output Load		CMOS 15pF Max.	
Rise and Fall Time	0.2Vdd↔0.8Vdd	10 nsec Max.	
Start-up time		10 msec Max.	
Aging (first year)		±2ppm / year Max.	